



Product End-of-Life Disassembly Instructions

Product Category: Desktops

Marketing Name / Model

[List multiple models if applicable.]

HP Elite Tower 600 G9 Desktop PC; HP Elite Tower 680 G9 Desktop PC; HP Elite Tower 800 G9 Desktop PC; HP Elite Tower 880 G9 Desktop PC; HP Z1 G9 Tower Desktop PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	<input checked="" type="checkbox"/> Main board (MB) PCB <input checked="" type="checkbox"/> Solid state drive (SSD) PCB <input type="checkbox"/> Wireless WAN module (WWAN) PCB <input type="checkbox"/> Touch module PCB <input checked="" type="checkbox"/> Power supply PCB <input checked="" type="checkbox"/> External Keyboard (KB) <input checked="" type="checkbox"/> External Mouse <input checked="" type="checkbox"/> Others: HDD PCB, Memory PCB	8
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	<input checked="" type="checkbox"/> RTC/CMOS battery <input type="checkbox"/> Others: _____	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: <input type="checkbox"/> screws <input type="checkbox"/> snaps <input type="checkbox"/> adhesive <input type="checkbox"/> other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	<input type="checkbox"/> Panel LCD	0

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	<input checked="" type="checkbox"/> Power Supply capacitor(s) or condenser(s)	1
External electrical cables and cords	<input checked="" type="checkbox"/> AC power cord <input type="checkbox"/> Audio, video or data cables <input type="checkbox"/> Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Hexagon Screw Driver	T-15
Crisscross Screw Driver	PH1
Soldering Iron	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Use T-15 screw driver to loose thumb screw and remove access panel.
2. Disconnect ODD power cable and ODD SATA cable from ODD.

3. Press the ODD's latch on ODD cage
4. Remove the ODD from ODD cage
5. Remove Front Bezel from chassis
6. Disconnect HDD power cable and HDD SATA cable from HDD.
7. Remove the driver cage from Chassis
8. Use T-15 screw driver to loose the screws of HDD and release HDD latch
9. Remove HDD from HDD cage
10. Disconnect system fan cable from MB
11. Disconnect Cooler Fan cable from MB
12. Use T-15 screw driver to loose the cooler screws and remove cooler from MB
13. Use T-15 screw driver to loose the screws and remove the fan
14. Separate the fan from CPU heat sink
15. Remove memory from the MB
16. Rotate the handle and open it up
17. Remove the CPU from the board
18. Remove SSD M.2 Card
19. Remove WLAN M.2 Card
20. Remove the battery from the system board
21. Use T-15 screw driver to loose the screws of MB from board
22. Remove MB from chassis
23. Remove speaker from Chassis
24. Remove System fan
25. Remove Front Antenna cable
26. Remove Rear Antenna cable
27. Use T-15 screw driver to loose the screws of PSU
28. Press the PSU's latch on chassis
29. Remove the PSU from chassis
30. Remove four screws covered
31. Remove the screw and open case
32. Use PH1 screw driver to remove FG screw
33. Disconnect fan connector and inlet connector
34. Loose screws and remove PCB from case
35. Loose screws and remove PSU fan
36. Use Soldering Iron to remove Ele-Cap from PCBA

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions \(hp.com\)](https://www.hp.com/End-of-Life-Product-Disassembly-Instructions)

Step1 Use T-15 screwdriver to Loose thumb screw and remove access panel	Step2 Disconnect ODD power cable and ODD SATA cable from ODD
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Step3 Press the ODD's latch on ODD cage



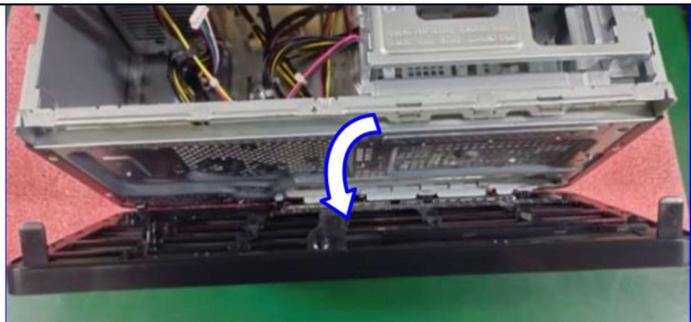
Step4 Remove the ODD from ODD cage



Step5 Remove front bezel from chassis



Step6 Loose the screws of Graphic card holder and rotate it up.



Step7 Remove the SATA cable and Power cable from cage



Step8 Use T-15 screwdriver to loose the screws of HDD and release HDD latch.



Step9 Remove HDD from HDD cage.



Step10 Disconnect system fan cable from MB



Step11 Disconnect Cooler Fan cable from MB

Step12 Use T-15 screw driver to loose the cooler screws and remove cooler from MB



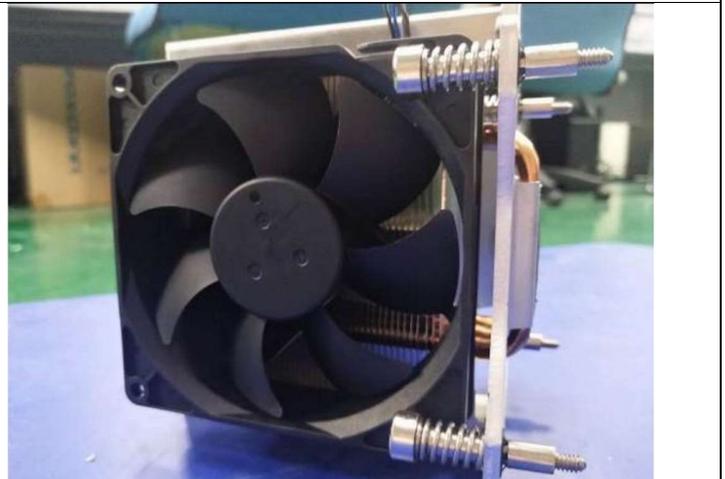
Step13 Use T-15 screwdriver to loose the screws and remove the fan



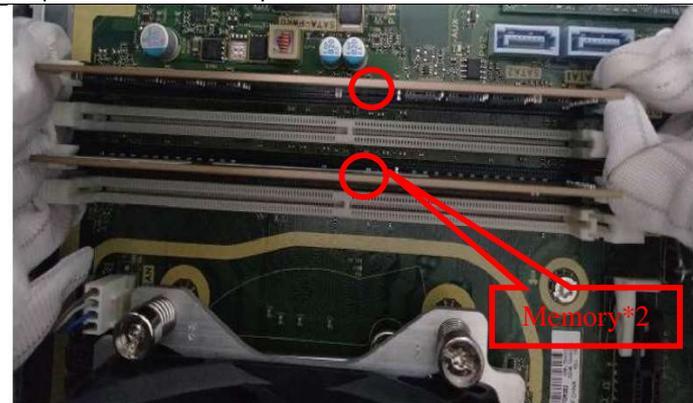
Step14 Separate the fan from CPU heat sink



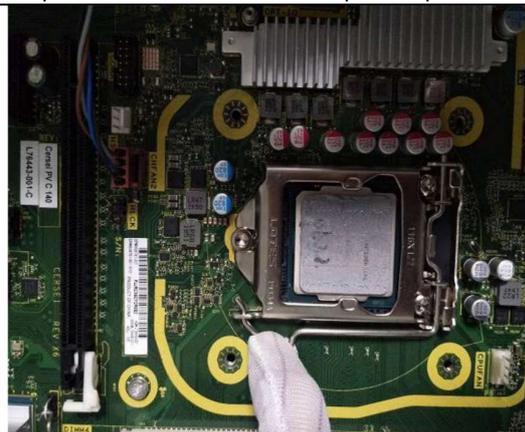
Step15 Remove memory from the MB



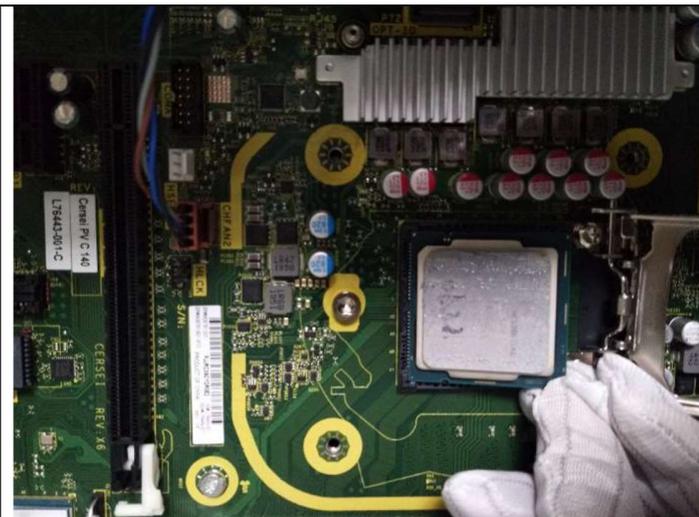
Step16 Rotate the handle and open it up



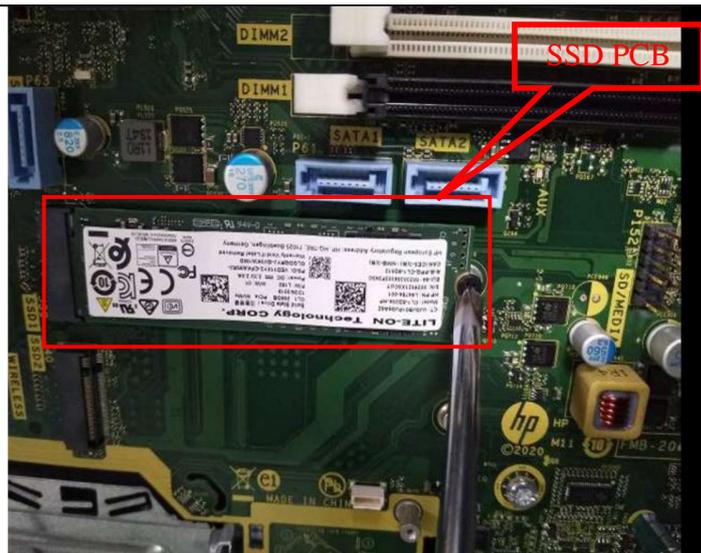
Step17 Remove the CPU from the board



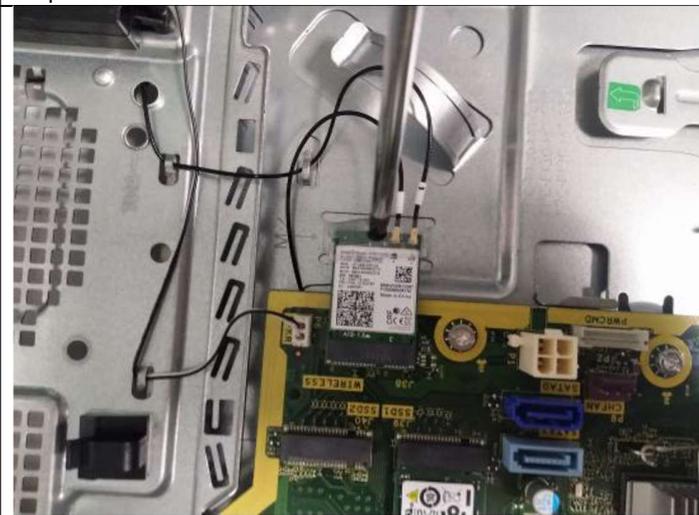
Step18 Remove SSD M.2 Card



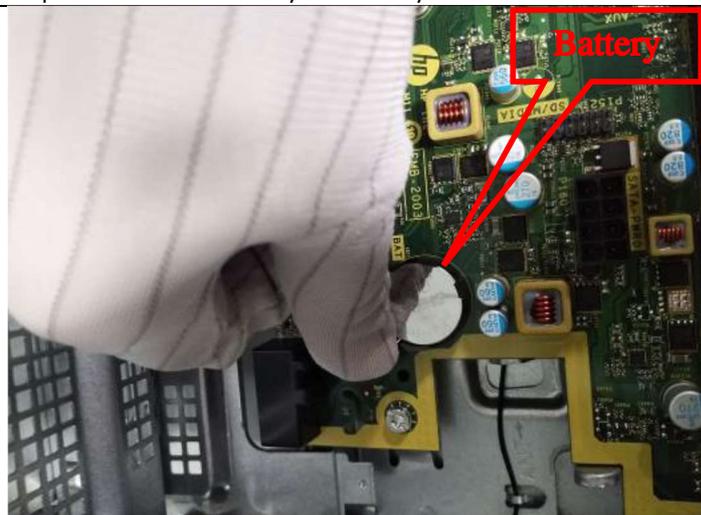
Step19 Remove WLAN M.2 Card



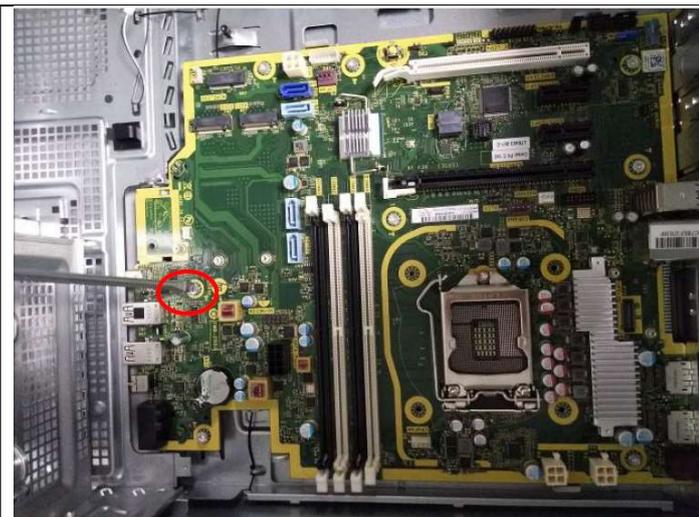
Step20 Remove the battery from the system board



Step21 Use T-15 screwdriver to loose the screws of MB from board



Step22 Remove MB from chassis



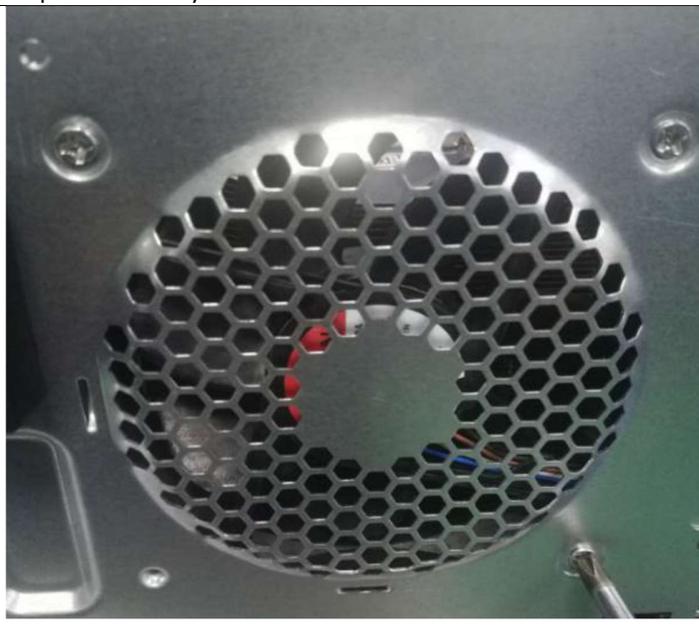
Step23 Remove speaker from Chassis



Step24 Remove System fan



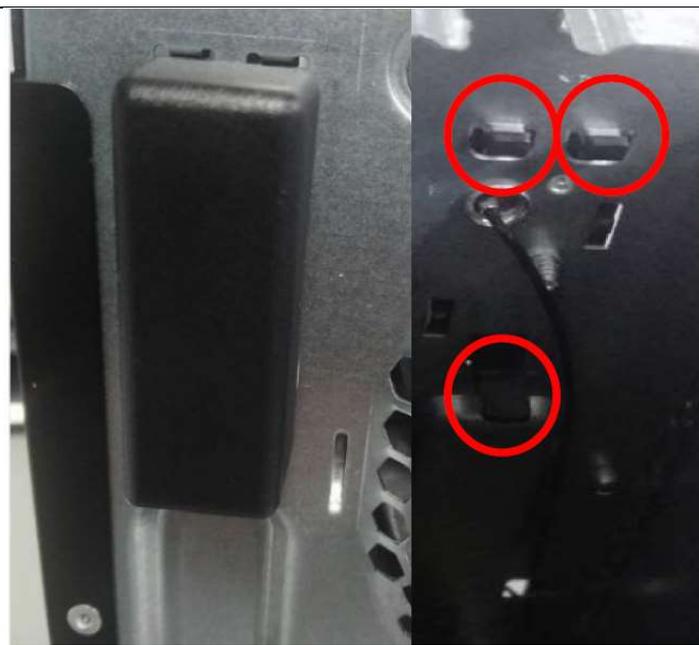
Step25 Remove Front Antenna cable



Step26 Remove Rear Antenna cable



Step27 Use T-15 screwdriver to loose the screws of Power supply



Step28 Press the PSU's latch on chassis



Step29 Remove the PSU from chassis



Step30 Remove screws covered



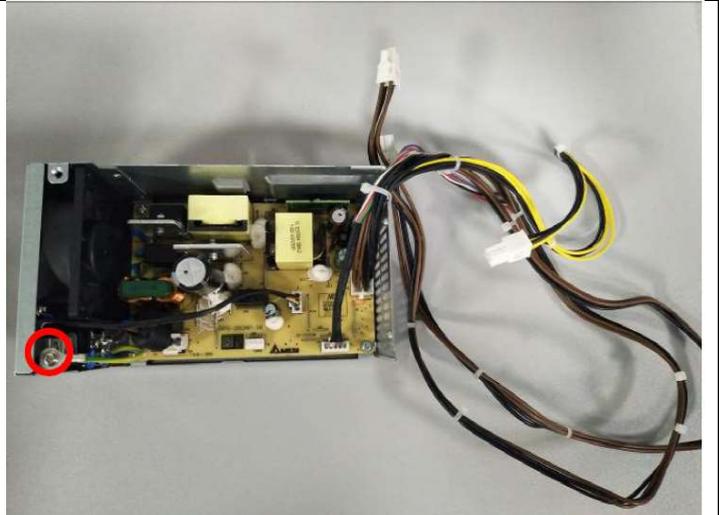
Step31 Remove PSU Cover



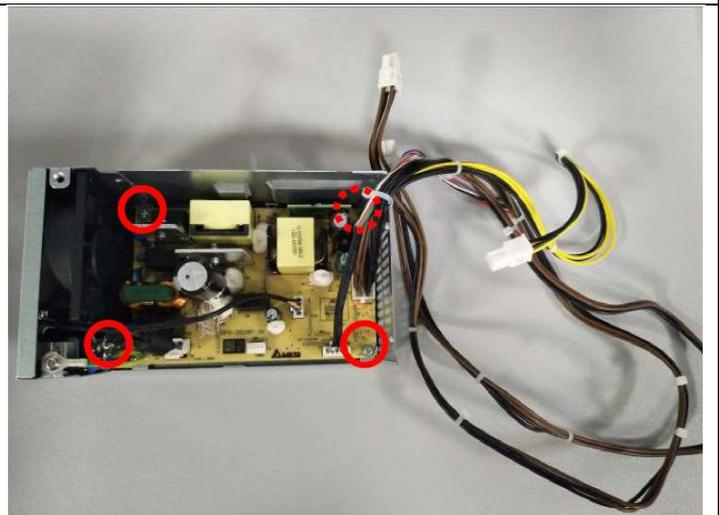
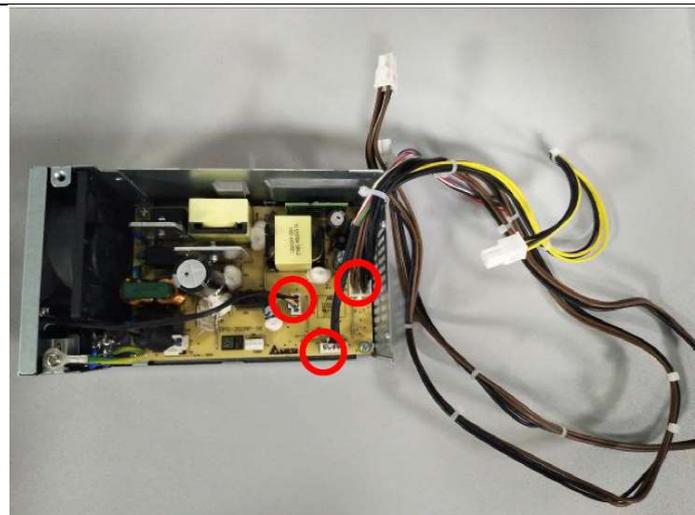
Step32 Use PH1 screw driver to remove FG screw



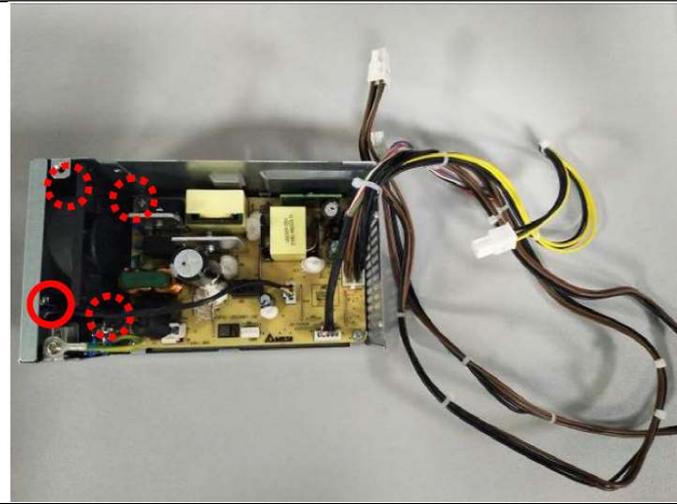
Step33 Disconnect fan connector and inlet connector



Step34 Loose screws and remove PCB from case



Step35 Loose fan screws and remove PSU fan



Step36 Heat the solder of the Ele-Cap of greater than 2.5cm in diameter or height and Remove it from PCBA

